

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	EMBEDDED PROCESSING/26/16067	
<b>1.3 Title of PCN</b>	ST Shenzhen (China) assembly site and HHgrace (China) Diffusion site additional source for STM32H74x and STM32H75x listed products in LQFP 20x20 and LQFP 24x24 packages.	
<b>1.4 Product Category</b>	STM32H742x, STM32H743x, STM32H750x and STM32H753x	
<b>1.5 Issue date</b>	2026-04-21	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	PIKE EMMA
<b>2.1.2 Phone</b>	+44 1628896111
<b>2.1.3 Email</b>	emma.pike@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Patrick AIDOUNE
<b>2.1.2 Marketing Manager</b>	Marie TOURNUT
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China), HHGrace (China)

**4. Description of change**

	Old	New
<b>4.1 Description</b>	<p>Current assembly sites (depending on package size) with Crolles Diffusion source:</p> <ul style="list-style-type: none"> <li>- AMKOR ATP (Philippine) Gold wire,</li> <li>- AMKOR ATP (Philippine) Copper Palladium wire,</li> <li>- ASE Kaohsiung (Taiwan) Gold wire,</li> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire ,</li> </ul> <p>You may refer to 16067_Additional information.pdf document for further details.</p>	<p>Current assembly sites (depending on package size) with Crolles Diffusion source:</p> <ul style="list-style-type: none"> <li>- AMKOR ATP (Philippine) Gold wire,</li> <li>- AMKOR ATP (Philippine) Copper Palladium wire,</li> <li>- ASE Kaohsiung (Taiwan) Gold wire,</li> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire ,</li> </ul> <p>Additional assembly site with HHGrace Diffusion Source for extended capacity:</p> <ul style="list-style-type: none"> <li>- ST Shenzhen (China) Copper Alloy wire .</li> </ul>
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No Impact on Form, Fit or Function	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	<p>Change is visible on the marking</p> <ul style="list-style-type: none"> <li>- Back-End Assembly Site code: <ul style="list-style-type: none"> <li>• GK : ST Shenzhen (China) New Assembly site</li> <li>• 7B : AMKOR ATP (Philippines)</li> <li>• AA : ASE KaoHsiung (Taiwan)</li> </ul> </li> <li>- Diffusion plant code WX: <ul style="list-style-type: none"> <li>• VQ : ST Crolles 300 (France)</li> <li>• Y5 : HHGrace WuXi (China) Fab 7 New Diffusion site</li> <li>• 2E : HHGrace WuXi (China) Fab 9 New Diffusion site</li> </ul> </li> </ul> <p>Please refer to PCN 16067_Additional information.pdf document for further details.</p>
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7. Timing / schedule	
7.1 Date of qualification results	2026-06-15
7.2 Intended start of delivery	2026-06-22
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16067 MDRF-GPAM-RER2506 PCN16067 - ST Shenzhen LQFP 20x20 and LQFP 24x24 packages - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-04-21

9. Attachments (additional documentations)	
16067 Public product.pdf 16067 MDRF-GPAM-RER2506 PCN16067 - ST Shenzhen LQFP 20x20 and LQFP 24x24 packages - reliability plan.pdf 16067 _Additional information.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H742IIT6	
	STM32H743IIT6	
	STM32H743ZGT6	
	STM32H743ZIT6	
	STM32H750ZBT6	
	STM32H753IIT6	
	STM32H753ZIT6	

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